

MAR 13 2008

Patent

Customer No. 31561

Docket No. 10544-US-PA

Application No.: 10/709,179

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Applicant : Chang et al.

Application No. : 10/709,179

Filed : April 19, 2004

For : STACK-TYPE MULTI-CHIP PACKAGE AND METHOD OF
FABRICATING BUMPS ON THE BACKSIDE OF A CHIP

Examiner : Ha, Nathan W.

Art Unit : 2814

TRANSMITTAL LETTER

+1-571-273-8300

(Via fax: 2+ 7 pages)

United States Patent and Trademark Office
 Customer Service Window
 Mail Stop Amendment
 Randolph Building
 401 Dulany Street
 Alexandria, VA 22314

Dear Sir,

In response to the Office Action dated December 13, 2007, please find the relevant paper in response to paper No. 20071209 as follows:

- Amendment and Response to Office Action in (7) pages.

The Applicant is NOT entitled to a status as a Small Entity; accordingly, please charge the following fees to the Deposit Account No.: 50-2620 (Order No.:10544-US-PA).

Fees are calculated as follows:

<input type="checkbox"/> Extra Claims Fee :						
	NUMBER FILED	CLAIMS FILED HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	FEE	
Total Claims	6	MINUS 20	= 0	× \$ 50	= \$ 0	
Independent Claims	1	MINUS 3	= 0	× \$ 210	= \$ 0	
<input type="checkbox"/> [1/2/3] month(s) extension of time is hereby requested.						= \$ 0
<input type="checkbox"/> Terminal Disclaimer Fee						= \$ 0
<input type="checkbox"/> Fee regarding Submission of an Information Disclosure Statement .						= \$ 0
Total:						= \$ 0

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If the payment is not fully covered in response thereof, the Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No.: 50-2620 (Order No.:10544-US-PA).

Thank you for your attention and assistance in this matter. If you have any questions, please feel free to contact the undersigned.

Respectfully Submitted,
JIANQ CHYUN Intellectual Property Office

Date: March 13, 2008By: Belinda Lee
Belinda Lee
Registration No.: 46,863

Please send future correspondence to:

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THE BACKSIDE OF A CHIPAMENDMENTS) Attorney Docket: 10544-US-PA
)

No fee is believed to be due. However, the Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No. 50-2620 (Order No.: 10544-US-PA)

AMENDMENTS AND RESPONSE TO OFFICE ACTION

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

The Office Action dated December 13, 2007, has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.